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- Qualified for Automotive Applications
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Low-Voltage Differential 50-Ω Line Drivers and Receivers
- Signaling Rates up to 500 Mbps
- Bus-Terminal ESD Exceeds 12 kV
- Operates From a Single 3.3 V Supply
- Low-Voltage Differential Signaling With Typical Output Voltages of 340 mV With a 50-Ω Load
- Valid Output With as Little as 50-mV Input Voltage Difference
- Propagation Delay Times
 - Driver: 1.7 ns Typ
 - Receiver: 3.7 ns Typ
- Power Dissipation at 200 MHz
 Driver: 50 mW Typical
 Receiver: 60 mW Typical
- LVTTL Input Levels Are 5 V Tolerant
- Driver Is High Impedance When Disabled or With V_{CC} < 1.5 V
- Receiver Has Open-Circuit Fail Safe

SN65LVDM050QDQ1 (Marked as LVDM050Q) (TOP VIEW) 14 15 1Y 1B 1**D** 13 16 VCC 1Z 12 1A 1D 2 15 DE 10 2Y 1R 14 🛛 1Y 3 11 2D RE 2Z 13 1Z 4 2R 12 DE 5 2 1A 2A 6 11 2Z 1 **1**R 1B 2B 10 2Y 7 RE GND 8 9 🛛 2 D 6 2A 7 2R 2B



description

The SN65LVDM050, and SN65LVDM051 are differential line drivers and receivers that use low-voltage differential signaling (LVDS) to achieve signaling rates as high as 500 Mbps (per TIA/EIA-644 definition). These circuits are similar to TIA/EIA-644 standard compliant devices (SN65LVDS) counterparts, except that the output current of the drivers is doubled. This modification provides a minimum differential output voltage magnitude of 247 mV across a 50- Ω load simulating two transmission lines in parallel. This allows having data buses with more than one driver or with two line termination resistors. The receivers detect a voltage difference of 50 mV with up to 1 V of ground potential difference between a transmitter and receiver.

The intended application of these devices and signaling techniques is point-to-point and multipoint, baseband data transmission over a controlled impedance media of approximately 100Ω of characteristic impedance. The transmission media may be printed-circuit board traces, backplanes, or cables.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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description (continued)

The SN65LVDM050Q and SN65LVDM051Q are characterized for operation from -40° C to 125° C. Additionally, Q1 suffixed parts are qualified in accordance with AEC-Q100 stress test qualification for integrated circuits.

AVAILABLE OPTIONS [†]				
	PACKAGE [‡]			
TA	SMALL OUTLINE (D)			
4000 1- 40500	SN65LVDM050QDQ1			
-40°C to 125°C	SN65LVDM051QDQ1			
+				

For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.
Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

NOTE:

The ultimate rate and distance of data transfer is dependent upon the attenuation characteristics of the media, the noise coupling to the environment, and other application-specific characteristics.

Function Tables

SN65LVDM050 and SN65LVDM051 RECEIVER

INPUTS	OUTPUT	
$V_{ID} = V_A - V_B$	RE	R
$V_{ID} \ge 50 \text{ mV}$	L	Н
–50 MV < V _{ID} < 50 mV	L	?
$V_{ID} \le -50 \text{ mV}$	L	L
Open	L	Н
Х	Н	Z

H = high level, L = low level, Z = high impedance, X = don't care

Function Tables (Continued)

SN65LVDM050 and SN65LVDM051 DRIVER

INPU	JTS	OUTI	PUTS
D	DE	Y	Z
L	Н	L	Н
Н	Н	Н	L
Open	Н	L	Н
Х	L	Z	Z

H = high level, L = low level, Z = high impedance, X = don't care



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equivalent input and output schematic diagrams



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absolute maximum ratings over operating free-air temperature (unless otherwise noted)[†]

Supply voltage range, V _{CC} (see Note 1)	
Voltage range (Y, Z, A, and B)	
Electrostatic discharge: Y, Z, A, B , and GND (see Note 2)	CLass 3, A:12 kV, B:600 V
All	Class 3, A:7 kV, B:500 V
Continuous power dissipation	see dissipation rating table
Storage temperature range	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	250°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.

2. Tested in accordance with MIL-STD-883C Method 3015.7.

		DISSIPATION RATING TAE	BLE	
PACKAGE	T _A ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C‡	T _A = 85°C POWER RATING	T _A = 125°C POWER RATING
D(8)	635 mW	5.1 mW/°C	330 mW	—
D(14)	987 mW	7.9 mW/°C	513 mW	—
D(16)	1110 mW	8.9 mW/°C	577 mW	223 mW
DGK	424 mW	3.4 mW/°C	220 mW	—
PW (14)	736 mW	5.9 mW/°C	383 mW	_
PW (16)	839 mW	6.7 mW/°C	437 mW	_

[‡]This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	3	3.3	3.6	V
High-level input voltage, VIH	2			V
Low-level input voltage, VIL			0.8	V
Magnitude of differential input voltage, VID	0.1		0.6	V
Common-mode input voltage, VIC (see Figure 6)	$\frac{ V_{\text{ID}} }{2}$:	$2.4 - \frac{ V_{ D } }{2}$	V
Operating free-air temperature, T _A	-40		V _{CC} -0.8	°C

device electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
			Drivers and receivers enabled, no receiver loads, driver RL = 50 Ω		19	27	
		SN65LVDM050	Drivers enabled, receivers disabled, RL = 50 Ω		16	24	mA
Icc	Supply current	Supply current	Drivers disabled, receivers enabled, no loads		4	6	
			Disabled		0.5	1	
		SN65LVDM051	Drivers enabled, no receiver loads, driver R _L = 50 Ω		19	27	~
		SINUSEV DIMUST	Drivers disabled, No loads		4	6	mA

[†] All typical values are at 25°C and with a 3.3 V supply.



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driver electrical characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{OD}	Differential output voltage magnitude				340	454	
$\Delta V_{OD} $	Change in differential output voltage magnitude betwee states	een logic	$R_L = 50 \Omega$, See Figure 1 and Figure 2	-50		50	mV
VOC(SS)	Steady-state common-mode output voltage			1.125	1.2	1.375	V
ΔVOC(SS)	Change in steady-state common-mode output voltage b logic states	dy-state common-mode output voltage between		-50		50	mV
VOC(PP)	Peak-to-peak common-mode output voltage				50		mV
		DE			-0.5	-20	
ін	High-level input current	D	V _{IH} = 5 V		2	20	μA
1		DE	N/- 00)/		-0.5	-10	
۱ _{IL}	Low-level input current	D	V _{IL} = 0.8 V		2	10	μA
			V_{OY} or $V_{OZ} = 0 V$		7	10	
los	Short-circuit output current		$V_{OD} = 0 V$		7	10	mA
			$V_{OD} = 600 \text{ mV}$			±1	•
IOZ High-impedance output current		AO = 0 A or ACC			±1	μA	
IO(OFF)	Power-off output current		$V_{CC} = 0 V$, $V_O = 3.6 V$			±1.5	μΑ
CIN	Input capacitance				3		pF

receiver electrical characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{IT+}	Positive-going differential input voltage threshold				50	
V _{IT} –	Negative-going differential input voltage threshold	See Figure 4 and Table 1	-50			mV
VOH	High-level output voltage	I _{OH} = -8 mA	2.4			V
VOL	Low-level output voltage	I _{OL} = 8 mA			0.4	V
	land compart (A on D innute)	$V_{I} = 0$	-2	-11	-20	
I	Input current (A or B inputs)	V _I = 2.4 V	-1.2	-3		μA
II(OFF)	Power-off input current (A or B inputs)	$V_{CC} = 0$			±20	μΑ
IIН	High-level input current (enables)	V _{IH} = 5 V			10	μΑ
IIГ	Low-level input current (enables)	$V_{IL} = 0.8 V$			10	μΑ
I _{OZ}	High-impedance output current	$V_{O} = 0 \text{ or } 5 V$			±10	μΑ
Cl	Input capacitance			5		pF

[†] All typical values are at 25°C and with a 3.3-V supply.



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driver switching characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN TYP [†]	MAX	UNIT
^t PLH	Propagation delay time, low-to-high-level output		1.7	3	ns
^t PHL	Propagation delay time, high-to-low-level output		1.7	3	ns
t _r	Differential output signal rise time	$R_{I} = 50\Omega$	0.6	1.2	ns
t _f	Differential output signal fall time	$C_{L}^{-} = 10 \text{ pF},$	0.6	1.2	ns
^t sk(p)	Pulse skew (t _{pHL} – t _{pLH})	See Figure 5	750		ps
^t sk(o)	Channel-to-channel output skew‡		100		ps
^t sk(pp)	Part-to-part skew§			1	ns
^t PZH	Propagation delay time, high-impedance-to-high-level output		6	10	ns
t _{PZL}	Propagation delay time, high-impedance-to-low-level output		6	10	ns
^t PHZ	Propagation delay time, high-level-to-high-impedance output	See Figure 6	4	10	ns
^t PLZ	Propagation delay time, low-level-to-high-impedance output		5	10	ns

[†] All typical values are at 25°C and with a 3.3-V supply.

 $t_{sk(0)}$ is the maximum delay time difference between drivers on the same device.

§ t_{sk(pp)} is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, at the same temperature, and have identical packages and test circuits.

receiver switching characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN TYP [†]	MAX	UNIT
^t PLH	Propagation delay time, low-to-high-level output		3.7	4.5	ns
t _{PHL}	Propagation delay time, high-to-low-level output	C _L = 10 pF, See Figure 7	3.7	4.5	ns
^t sk(p)	Pulse skew (t _{pHL} – t _{pLH})		0.1		ns
^t sk(o)	Channel-to-channel output skew		0.2		ns
^t sk(pp)	Part-to-part skew [‡]			1	ns
t _r	Output signal rise time	C _L = 10 pF,	0.7	1.5	ns
t _f	Output signal fall time	See Figure 7	0.9	1.5	ns
^t PZH	Propagation delay time, high-level-to-high-impedance output		2.5		ns
t _{PZL}	Propagation delay time, low-level-to-low-impedance output		2.5		ns
^t PHZ	Propagation delay time, high-impedance-to-high-level output	See Figure 8	7		ns
t _{PLZ}	Propagation delay time, low-impedance-to-high-level output		4		ns

[†] All typical values are at 25°C and with a 3.3-V supply.

t_{sk(pp)} is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, at the same temperature, and have identical packages and test circuits.



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PARAMETER MEASUREMENT INFORMATION

driver



Figure 1. Driver Voltage and Current Definitions



NOTE A: All input pulses are supplied by a generator having the following characteristics: t_r or $t_f \le 1$ ns, pulse repetition rate (PRR) = 50 Mpps, pulse width = 10 ± 0.2 ns . CL includes instrumentation and fixture capacitance within 0,06 mm of the D.U.T.



Figure 2. Test Circuit, Timing, and Voltage Definitions for the Differential Output Signal

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PARAMETER MEASUREMENT INFORMATION

driver (continued)



NOTE A: All input pulses are supplied by a generator having the following characteristics: t_r or $t_f \le 1$ ns, pulse repetition rate (PRR) = 50 Mpps, pulse width = 10 ± 0.2 ns . C_L includes instrumentation and fixture capacitance within 0,06 mm of the D.U.T. The measurement of V_{OC(PP)} is made on test equipment with a –3 dB bandwidth of at least 300 MHz.

Figure 3. Test Circuit and Definitions for the Driver Common-Mode Output Voltage



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PARAMETER MEASUREMENT INFORMATION

receiver



Figure 4. Receiver Voltage Definitions

	VOLTAGES (V)	RESULTING DIFFERENTIAL INPUT VOLTAGE (mV)	RESULTING COMMON- MODE INPUT VOLTAGE (V)
VIA	V _{IB}	V _{ID}	VIC
1.225	1.175	50	1.2
1.175	1.225	-50	1.2
2.375	2.325	50	2.35
2.325	2.375	-50	2.35
0.05	0	50	0.05
0	0.05	-50	0.05
1.5	0.9	600	1.2
0.9	1.5	-600	1.2
2.4	1.8	600	2.1
1.8	2.4	-600	2.1
0.6	0	600	0.3
0	0.6	-600	0.3

Table 1. Receiver Minimum and Maximum Input Threshold Test Voltages



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PARAMETER MEASUREMENT INFORMATION

driver





Figure 5. Timing Test Circuit

NOTE A: All input pulses are supplied by a generator having the following characteristics: t_r or $t_f \le 1$ ns, pulse repetition rate (PRR) = 0.5 Mpps, pulse width = 500 ± 10 ns . C_L includes instrumentation and fixture capacitance within 0,06 mm of the D.U.T.

Figure 6. Enable and Disable Time Circuit and Definitions



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PARAMETER MEASUREMENT INFORMATION

receiver



NOTE A: All input pulses are supplied by a generator having the following characteristics: t_r or $t_f \le 1$ ns, pulse repetition rate (PRR) = 50 Mpps, pulse width = 10 ± 0.2 ns. CL includes instrumentation and fixture capacitance within 0,06 mm of the D.U.T.

Figure 7. Timing Test Circuit and Waveforms



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PARAMETER MEASUREMENT INFORMATION

receiver (continued)



NOTE A: All input pulses are supplied by a generator having the following characteristics: t_f or $t_f \le 1$ ns, pulse repetition rate (PRR) = 0.5 Mpps, pulse width = 500 ± 10 ns. C_L includes instrumentation and fixture capacitance within 0,06 mm of the D.U.T.



Figure 8. Enable/Disable Time Test Circuit and Waveforms



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TYPICAL CHARACTERISTICS



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TYPICAL CHARACTERISTICS



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APPLICATION INFORMATION

The devices are generally used as building blocks for high-speed point-to-point data transmission. Ground differences are less than 1 V with a low common-mode output and balanced interface for very low noise emissions. Devices can interoperate with RS-422, PECL, and IEEE-P1596. Drivers/receivers maintain ECL speeds without the power and dual supply requirements.



Figure 18. Data Transmission Distance Versus Rate



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APPLICATION INFORMATION

fail safe

One of the most common problems with differential signaling applications is how the system responds when no differential voltage is present on the signal pair. The LVDS receiver is like most differential line receivers, in that its output logic state can be indeterminate when the differential input voltage is between –50 mV and 50 mV and within its recommended input common-mode voltage range. TI's LVDS receiver is different, however, in how it handles the open-input circuit situation.

Open-circuit means that there is little or no input current to the receiver from the data line itself. This could be when the driver is in a high-impedance state or the cable is disconnected. When this occurs, the LVDS receiver pulls each line of the signal pair to near V_{CC} through 300-k Ω resistors as shown in Figure 18. The fail-safe feature uses an AND gate with input voltage thresholds at about 2.3 V to detect this condition and force the output to a high-level, regardless of the differential input voltage.



Figure 19. Open-Circuit Fail Safe of the LVDS Receiver

It is only under these conditions that the output of the receiver is valid with less than a 50-mV differential input voltage magnitude. The presence of the termination resistor, Rt, does not affect the fail-safe function as long as it is connected as shown in the figure. Other termination circuits may allow a dc current to ground that could defeat the pullup currents from the receiver and the fail-safe feature.





PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	•	Eco Plan	Lead finish/	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	Ball material	(3)		(4/5)	
							(6)				
SN65LVDM050QDG4Q1	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVDM050Q	Samples
SN65LVDM050QDQ1	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVDM050Q	Samples
SN65LVDM050QDRG4Q1	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVDM050Q	Samples
SN65LVDM050QDRQ1	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVDM050Q	Samples
SN65LVDM051QDQ1	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVDM051Q	Samples
SN65LVDM051QDRG4Q1	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVDM051Q	Samples
SN65LVDM051QDRQ1	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVDM051Q	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



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PACKAGE OPTION ADDENDUM

10-Dec-2020

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN65LVDM050-Q1, SN65LVDM051-Q1 :

• Catalog: SN65LVDM050, SN65LVDM051

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65LVDM050QDRQ1	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN65LVDM051QDRG4Q1	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN65LVDM051QDRQ1	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

14-Aug-2019



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65LVDM050QDRQ1	SOIC	D	16	2500	350.0	350.0	43.0
SN65LVDM051QDRG4Q1	SOIC	D	16	2500	350.0	350.0	43.0
SN65LVDM051QDRQ1	SOIC	D	16	2500	350.0	350.0	43.0

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



4211283-4/E 08/12

D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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